LAUNCHING PHOTO HEAD FOR ADVANCED PACKAGING - LLS 04

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Visitech is proud to present the LLS 04 on the Productronica in Munchen in November 2017. The LUXBEAM® Lithography system, a subsystem for Direct Imaging machine builders, is already used in solder mask and inner/outer layer applications, with line/space down to 10 um.

The new LLS 04 can achieve a 4 um line/space and comes with a powerful 405 nm light source. Further, an upgraded fast and accurate autofocus is included, capable of delivering state-of-the-art throughput.

«With the new LLS 04, we also cover more of the advanced packaging market in DI», says Director of Business Development Oyvind Tafjord.

Learn more about our subsystems for advanced packaging:

direct imaging lithography